

### **Amendments to the Claims**

Claim 1 **(Previously Presented)** A holding unit for holding a substrate, said holding unit comprising:

a holder plate; and

a vacuum suction member adapted to be brought into contact with a peripheral portion of a surface of the substrate to suck the substrate, said vacuum suction member having no contact with regions of the substrate other than the peripheral portion,

wherein said holder plate, said vacuum suction member and the substrate define a space which can be purged by blowing N<sub>2</sub> gas thereinto so that etchant is prohibited from entering into the space during processing of the substrate, and

wherein said holder plate has a purging aperture for blowing the N<sub>2</sub> gas into the space defined by said holder plate, said vacuum suction member and the substrate, said purging aperture being connected to a N<sub>2</sub> source by a tube located in a cylindrical rotary shaft mounted to said holder plate.

Claim 2 **(Original)** A holding unit of claim 1, wherein said vacuum suction member is shaped so as to surround an element forming region of the substrate, thereby preventing processing from being applied to the element forming region.

Claim 3 **(Original)** A holding unit of claim 1, wherein said vacuum suction member has an annular groove and an exhaust path formed therein, said annular groove being open in a side facing the substrate, and said exhaust path opening to said annular groove.

Claim 4 **(Original)** A holding unit of claim 1, wherein a material forming a portion of said vacuum suction member to be brought into contact with the substrate has a hardness lower than that of the substrate.

Claim 5 **(Previously Presented)** A processing apparatus for processing a substrate, said processing apparatus comprising:

a holding unit of claim 1; and

a surface processing unit for processing another surface of the substrate held by said holding unit.

**Claim 6 (Original)** A processing apparatus of claim 5, further comprising a unit operable to perform at least one of cleaning and drying of the substrate.

**Claim 7 (Original)** A processing apparatus of claim 5, further comprising a dipping bath for dipping the substrate held by said holding unit.

**Claim 8 (Previously Presented)** A processing apparatus of claim 5, further comprising an evaluation unit operable to check a condition of the substrate after processing and to determine a resultant condition achieved by processing the other surface of the substrate.

**Claim 9 (Canceled)**

**Claim 10 (Original)** A holding unit of claim 3, wherein said annular groove is substantially V-shaped.

**Claim 11 (Original)** A holding unit of claim 3, wherein said annular groove is substantially rectangular shaped.

**Claim 12 (Original)** A holding unit of claim 1, wherein said vacuum suction member comprises at least two ring-shaped members forming at least one annular groove therebetween, said annular groove being open in a side facing the substrate.

**Claims 13-24 (Canceled)**